2012 VAIL Computer Elements Workshop
June 24-27, 2012
http://projects.ccec.unf.edu/vail

New Dimensions
Program Chair: Steve Miller, NetApp, scm@netapp.com
Program Co-Chair: Yahya Sotoudeh, Intel, yahya.sotoudeh@intel.com

Sunday June 24 5 PM Registration, Dinner and Keynote Presentation (8:00 PM – 9:15 PM)

Next Generation
Key Note Chair: Jim Hughes, jphughes@mac.com Key Note Speaker: Jim Hughes

Monday June 25
Session 1: Internet of Things
8:30 AM – 12:00 noon
1. Reliability of Distributed Things
   Marc Stiegler, HP Labs, erights@google.com
2. WWW Neural Network
   Don Banks, Cisco, donbanks@cisco.com
3. Shipping Container Integrity Monitoring
   Vipul Gupta, Oracle, vipul.x.gupta@oracle.com
4. Mobile Code on Mutually Suspicious Devices
   Mark Miller, Google, erights@google.com

Session 2: I/O & Interconnect
1030 pM – 4:30 PM
1. Auto Commit Memory
   Nisha Talagala, Fusion-IO, ntalagala@fusionio.com
2. Big Data Futures
   Gaurav Makka, NetApp, gaurav.makkar@netapp.com
3. System Interconnect Innovation
   Muhannad Bakir, Ga Tech, muhannad.bakir@miric.gatech.edu
4. CMOS & Si Photonics Hybrid Integration
   Jack Cunningham, Oracle, john.cunningham@oracle.com

Session 3: Panel-Emerging Memory
8:00 PM – 10:15 PM
1. In-package Memory
   Pete Vogt, Intel, pete.d.vogt@intel.com

Tuesday June 26
Session 4: Consumer Electronics
8:30 AM – 12:00 noon
1. Biomed CMOS Image Sensors
   Jun Ohta, NAIST, ohta@ms.naist.jp
2. FPGA Ultra Low Power
   Takayuki Suyama, NTT, suyama.takayuki@lab.ntt.co.jp
3. Sensor Networks
   Atsushi Hasegawa, Renesas, atsushi.hasegawa.gx@renesas.com

Session 5: Panel-Medical Electronics
8:00 PM – 10:15 PM
1. Electronic Stimulation Knee Rehab
   Herbie Kirn, llkirn@articulatelabs.com, Articulate Labs

Wednesday June 27
Session 6: 22 nm & More
8:30 AM – 12:00 noon
1. Silicon Horizons
   Dinesh Somasekhar, Global Foundries, dinesh.somasekhar@globalfoundries.com
2. Embedded Multi-Core Challenges
   Hang Nguyen, Intel, hang.t.nguyem@intel.com

Planning Session: Vail 2013, 4PM – 5:30 PM All invited to participate.

Session 6: 22 nm & More
8:30 AM – 12:00 noon
1. Silicon Horizons
   Dinesh Somasekhar, Global Foundries, dinesh.somasekhar@globalfoundries.com
2. Embedded Multi-Core Challenges
   Hang Nguyen, Intel, hang.t.nguyem@intel.com

Wednesday June 27
Session 6: 22 nm & More
8:30 AM – 12:00 noon
1. Silicon Horizons
   Dinesh Somasekhar, Global Foundries, dinesh.somasekhar@globalfoundries.com
2. Embedded Multi-Core Challenges
   Hang Nguyen, Intel, hang.t.nguyem@intel.com

Planning Session: Vail 2013, 4PM – 5:30 PM All invited to participate.

Session 5: Panel-Medical Electronics
8:00 PM – 10:15 PM
1. Electronic Stimulation Knee Rehab
   Herbie Kirn, llkirn@articulatelabs.com, Articulate Labs

Wednesday June 27
Session 6: 22 nm & More
8:30 AM – 12:00 noon
1. Silicon Horizons
   Dinesh Somasekhar, Global Foundries, dinesh.somasekhar@globalfoundries.com
2. Embedded Multi-Core Challenges
   Hang Nguyen, Intel, hang.t.nguyem@intel.com

Planning Session: Vail 2013, 4PM – 5:30 PM All invited to participate.